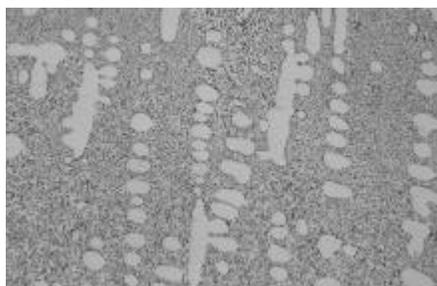


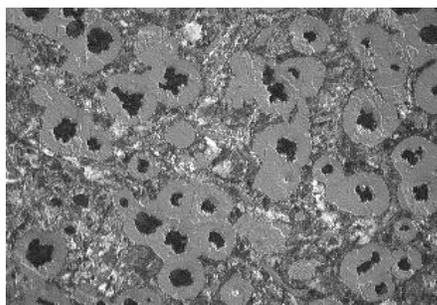
by Donald Zipperian, Ph.D.

## Etching - Enhancing Microstructures

The purpose of etching is to optically enhance microstructural features such as grain size and phase features. Etching selectively alters these microstructural features based on composition, stress, or crystal structure. The most common technique for etching is selective chemical etching and numerous formulations have been used over the years. Other techniques such as molten salt, electrolytic, thermal and plasma etching have also found specialized applications.



Aluminum-Silicon Alloy, B.F. 200X,  
Kellers etchant



Cast Iron, B.F. 100X, 2% Nital

## Etching Basics

**Chemical etching** selectively attacks specific microstructural features. It generally consists of a mixture of acids or bases with oxidizing or reducing agents. To understand the basics of chemical etching, the relationship between pH and Eh (oxidation/reduction potentials), often known as Eh-pH diagrams or Pourbaix diagrams can be used.

## Etchant Procedures

**Specimen Preparation** - proper metallographic specimen preparation is required to avoid artifacts such as an altered grain structure or a smeared microstructural surface.

Common etching techniques include swabbing and immersion. Swabbing is less aggressive for more controlled attack, however is also less uniform. Immersion involves submerging the specimen and produces a more uniform etching, however it is also easier to either under or over etch.

For difficult to etch specimens, the etching rate can be enhanced with temperature, ultrasonics, electrolytic or microwave energy.

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### Considerations for chemical etching

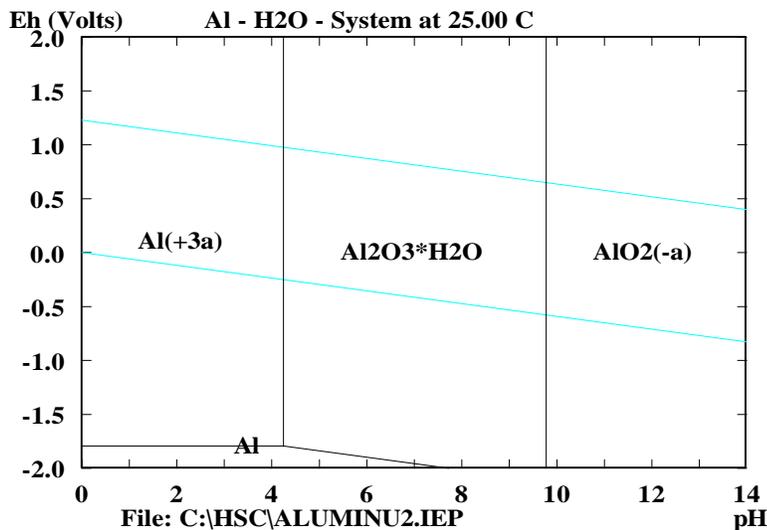
- Chemical concentration
- Etchant temperature
- Agitation
- Specimen surface preparation

## Pourbaix Diagrams

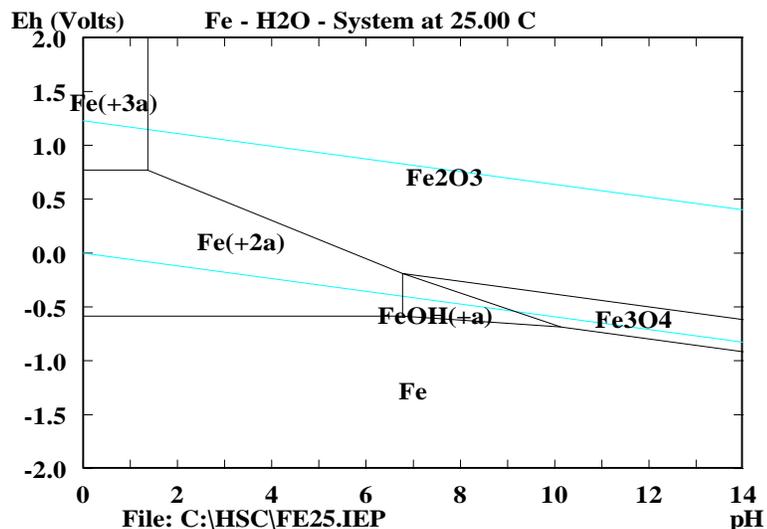
Pourbaix diagrams are thermodynamic diagrams which show the ability of metals to be attacked, dissolved or corroded at various pH and oxidation conditions. Although useful, they are limited because they do not address the kinetics of dissolution, which is often determined by experimental analysis or previous experience.

The upper left diagram is the Pourbaix diagram for the aluminum-water system. This diagram shows that aluminum will be attacked at pH values below 4 and at pH values above 10. From etching experiments high pH values attack the aluminum at a faster rate than at lower pH values.

Likewise, the Pourbaix for the iron-water system is shown in the lower left diagram. As indicated iron forms iron oxides at higher pH values forming iron oxides and therefore etching at higher pH values does not produce the best etching conditions. Also the iron dissolves to form either a Fe+3 or a Fe+2 species depending upon the oxidation potential. Note the most common etchant for iron and steels is nital which contains an oxidizing acid (nitric acid).



Pourbaix diagram for aluminum-water system.



Pourbaix diagram for iron-water system.

**Common Chemical Etchants**

| <b>Etchant</b>           | <b>Composition</b>  | <b>Conc.</b>                          | <b>Conditions</b>                                 | <b>Comments</b>  |
|--------------------------|---|---------------------------------------|---|--|
| <b>Keller's Etch</b>     | Distilled water<br>HNO <sub>3</sub><br>HCl<br>HF                                      | 190 ml<br>5 ml<br>3 ml<br>2 ml        | 10-30 second immersion.<br>Use only fresh etchant |  |
| <b>Kroll's Reagent</b>   | Distilled water<br>HNO <sub>3</sub><br>HF   | 92 ml<br>6 ml<br>2 ml                 | 15 seconds  |  |
| <b>Nital</b>             | Ethanol<br>HNO <sub>3</sub>   | 100 ml<br>1-10 ml                     | Seconds to minutes                                |  |
| <b>Kallings Reagent</b>  | Distilled water<br>Copper chloride (CuCl <sub>2</sub> )<br>HCl<br>Ethanol or methanol | 40 ml<br>2 grams<br>40 ml<br>40-80 ml | Immerse or swab for few seconds to a few minutes  |  |
| <b>Lepito's Reagent</b>  | Acetic acid<br>Nitric acid  | 50 ml<br>50 ml                        | Swab  |  |
| <b>Marble's Reagent</b>  | Distilled Water<br>HCl<br>Copper sulfate (CuSO <sub>4</sub> )                         | 50 ml<br>50 ml<br>10 grams            | Immersion or swab, etch for a few seconds         |  |
| <b>Murakami Reagent</b>  | Distilled Water<br>K <sub>3</sub> Fe(CN) <sub>6</sub><br>NaOH or KOH                  | 100 ml<br>10 grams<br>10 grams        | Immerse or swab for seconds to minutes            | Use fresh  |
| <b>Picral</b>            | Ethanol<br>Picric acid  | 100 ml<br>2-4 grams                   | Seconds to minutes                                | Do not let etchant crystallize or dry - <b>explosive</b> |
| <b>Vilella's Reagent</b> | Glycerol<br>HNO <sub>3</sub><br>HCl   | 45 ml<br>15 ml<br>30 ml               | Seconds to minutes                                |  |

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